

POLISHING APPARATUS AND POLISHING METHOD

ABSTRACT OF THE DISCLOSURE

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A polishing apparatus and a polishing method which can reduce the amount of consumption of the polishing agent and scratches caused on the object to be polished due to an increase of the particle size in the polishing agent. The polishing apparatus has a polishing head which is provided with a polishing agent receiving unit, a holding means for holding an object to be polished in a holding recess, a contact portion which is positioned at the periphery of the holding recess, a feed port for feeding the polishing agent from the polishing agent receiving portion into the closed space, a vibration imparting means for imparting vibration to the polishing agent, and a valve means provided with a valve for opening and closing the feed port.